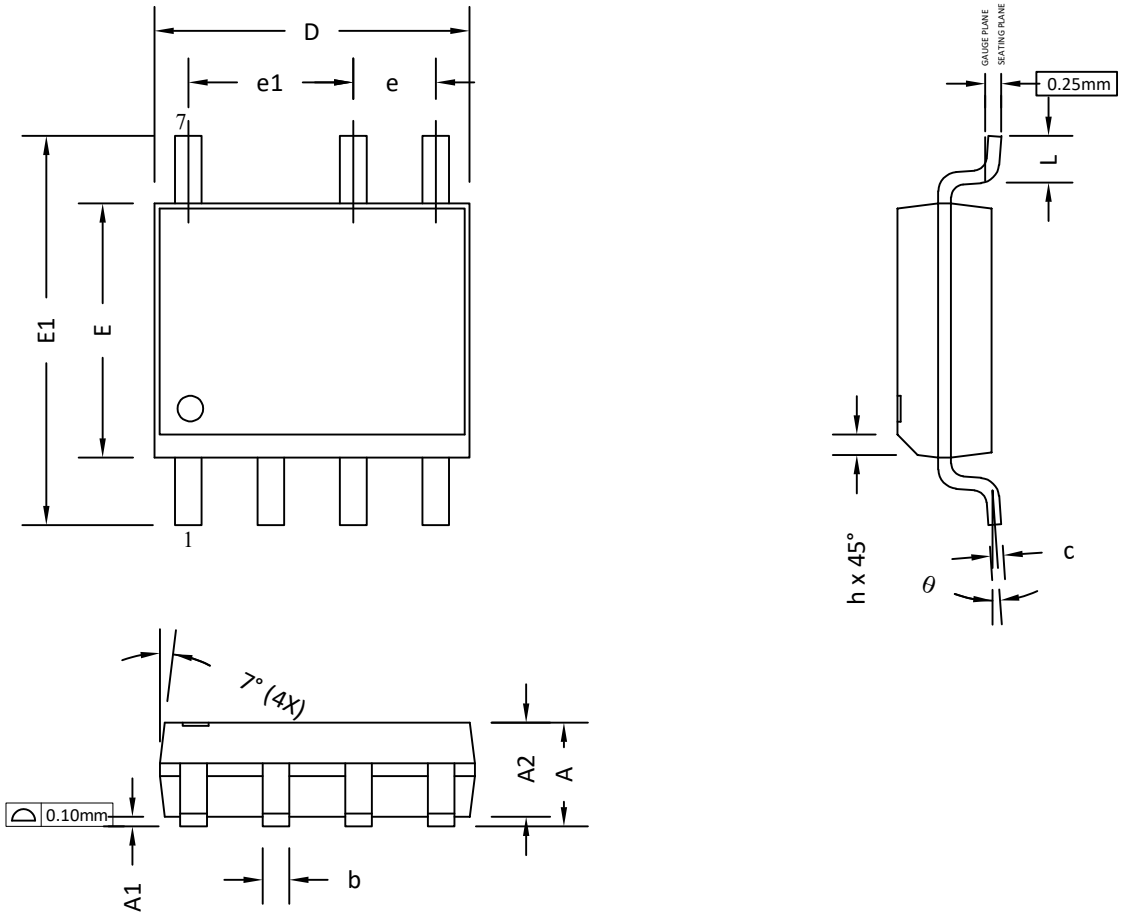
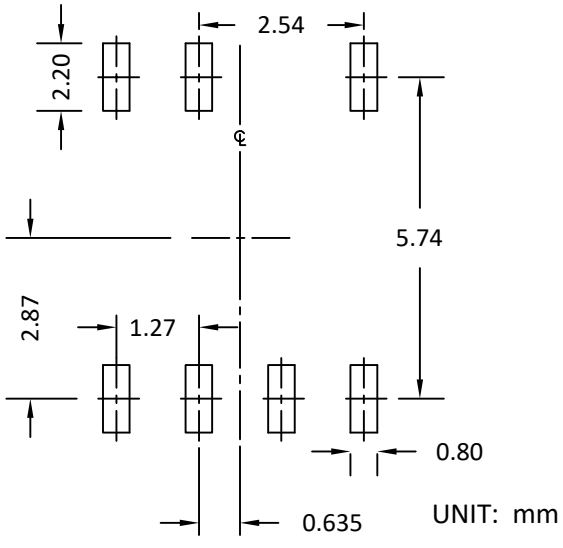
ALPHA & OMEGA SEMICONDUCTOR

Document No.	PO-00218
Version	B

SO7 PACKAGE OUTLINE



RECOMMENDED LAND PATTERN



SYMBOLS	DIM. IN MM			DIM. IN INCH		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	1.350	1.650	1.75	0.053	0.065	0.069
A1	0.100	---	0.25	0.004	---	0.010
A2	1.250	1.500	1.65	0.049	0.059	0.065
b	0.310	---	0.510	0.012	---	0.020
c	0.170	---	0.250	0.007	---	0.010
D	4.800	4.900	5.000	0.189	0.193	0.197
E	3.800	3.900	4.000	0.150	0.154	0.157
e	1.27BSC			0.050BSC		
e1	2.54BSC			0.100BSC		
E1	5.80	6.000	6.20	0.228	0.236	0.244
h	0.25	---	0.50	0.010	---	0.020
L	0.40	---	1.27	0.016	---	0.050
Θ	0°	---	8°	0°	---	8°

NOTE
1. ALL DIMENSIONS ARE IN MILLMETERS.
2. DIMENSIONS ARE INCLUSIVE OF PLATING.
3. PACKAGE BODY SIZES EXCLUDE MOLD FLASH AND GATE BURRS.
   MOLD FLASH AT THE NON-LEAD SIDES SHOULD BE LESS THAN 6 MILS EACH.
4. DIMENSION L IS MEASURED IN GAUGE PLANE.
5. CONTROLLING DIMENSION IS MILLIMETER.
   CONVERTED INCH DIMENSIONS ARE NOT NECESSARILY EXACT.